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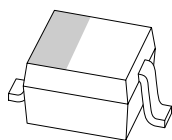
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Kind regards,

Team Nexperia



# PMEG1020EA

2 A ultra low  $V_F$  MEGA Schottky barrier rectifier

Rev. 04 — 30 December 2008

Product data sheet

## 1. Product profile

### 1.1 General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in SOD323 (SC-76) very small Surface-Mounted Device (SMD) plastic package.

### 1.2 Features

- Forward current:  $I_F \leq 2$  A
- Reverse voltage:  $V_R \leq 10$  V
- Ultra low forward voltage
- Very small SMD plastic package

### 1.3 Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch Mode Power Supply (SMPS)
- Reverse polarity protection
- Low power consumption applications

### 1.4 Quick reference data



Table 1. Quick reference data

| Symbol | Parameter       | Conditions          | Min                   | Typ | Max | Unit |
|--------|-----------------|---------------------|-----------------------|-----|-----|------|
| $I_F$  | forward current | $T_{sp} \leq 55$ °C | -                     | -   | 2   | A    |
| $V_R$  | reverse voltage |                     | -                     | -   | 10  | V    |
| $V_F$  | forward voltage | $I_F = 1$ A         | <a href="#">[1]</a> - | 280 | 350 | mV   |

[1] Pulse test:  $t_p \leq 300$   $\mu$ s;  $\delta \leq 0.02$ .

## 2. Pinning information

Table 2. Pinning

| Pin | Description | Simplified outline  | Graphic symbol  |
|-----|-------------|---|---|
| 1   | cathode     |  | <br>sym001 |
| 2   | anode       |   |   |

[1] The marking bar indicates the cathode.

## 3. Ordering information

Table 3. Ordering information

| Type number | Package |  |         |
|-------------|---------|--|---------|
|             | Name    | Description                              | Version |
| PMEG1020EA  | SC-76   | plastic surface-mounted package; 2 leads | SOD323  |

## 4. Marking

Table 4. Marking codes

| Type number | Marking code |
|-------------|--------------|
| PMEG1020EA  | E2           |

## 5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol    | Parameter                           | Conditions                                 | Min | Max  | Unit               |
|-----------|-------------------------------------|--|-----|------|--------------------|
| $V_R$     | reverse voltage                     |  | -   | 10   | V                  |
| $I_F$     | forward current                     | $T_{sp} \leq 55\text{ }^{\circ}\text{C}$   | -   | 2    | A                  |
| $I_{FRM}$ | repetitive peak forward current     | $t_p \leq 1\text{ ms}$ ; $\delta \leq 0.5$ | -   | 3.2  | A                  |
| $I_{FSM}$ | non-repetitive peak forward current | square wave;<br>$t_p = 8\text{ ms}$        | -   | 9    | A                  |
| $T_j$     | junction temperature                |  | -   | 150  | $^{\circ}\text{C}$ |
| $T_{amb}$ | ambient temperature                 |  | -65 | +150 | $^{\circ}\text{C}$ |
| $T_{stg}$ | storage temperature                 |  | -65 | +150 | $^{\circ}\text{C}$ |

## 6. Thermal characteristics

**Table 6. Thermal characteristics**

| Symbol         | Parameter  | Conditions  | Min   | Typ | Max | Unit |
|----------------|--|-------------|-------|-----|-----|------|
| $R_{th(j-a)}$  | thermal resistance from junction to ambient      | in free air | [1] - | -   | 450 | K/W  |
|                |  |             | [2] - | -   | 210 | K/W  |
| $R_{th(j-sp)}$ | thermal resistance from junction to solder point |             | [3] - | -   | 90  | K/W  |

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB with copper clad  $10 \times 10$  mm.

[3] Soldering point of cathode tab.

## 7. Characteristics

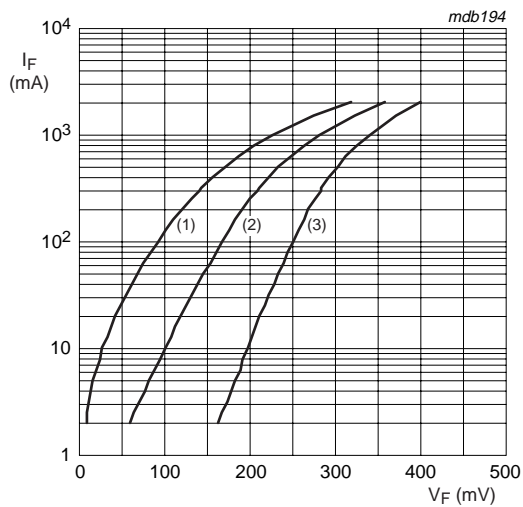
**Table 7. Characteristics**

$T_{amb} = 25^\circ\text{C}$  unless otherwise specified.

| Symbol | Parameter         | Conditions               | Min | Typ | Max | Unit |
|--------|-------------------|--------------------------|-----|-----|-----|------|
| $V_F$  | forward voltage   | [1]                      |     |     |     |      |
|        |                   | $I_F = 0.01$ A           | -   | 100 | 130 | mV   |
|        |                   | $I_F = 0.1$ A            | -   | 170 | 200 | mV   |
|        |                   | $I_F = 1$ A              | -   | 280 | 350 | mV   |
|        |                   | $I_F = 2$ A              | -   | 350 | 460 | mV   |
| $I_R$  | reverse current   | [2]                      |     |     |     |      |
|        |                   | $V_R = 5$ V              | -   | 0.7 | 2   | mA   |
|        |                   | $V_R = 8$ V              | -   | 1   | 2.5 | mA   |
|        |                   | $V_R = 10$ V             | -   | 1.2 | 3   | mA   |
| $C_d$  | diode capacitance | $V_R = 5$ V; $f = 1$ MHz | -   | 37  | 45  | pF   |

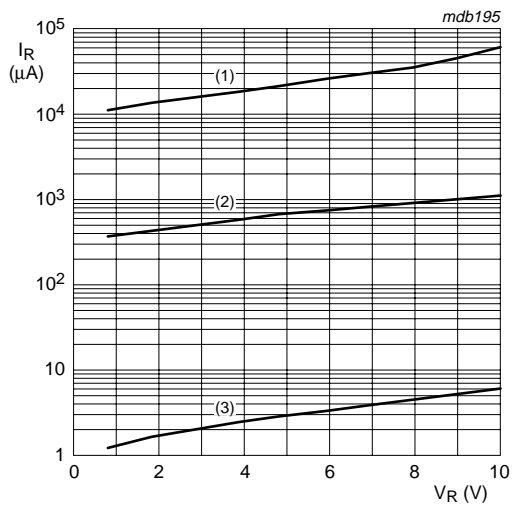
[1] Pulse test:  $t_p \leq 300$   $\mu\text{s}$ ;  $\delta \leq 0.02$ .

[2] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses  $P_R$  are a significant part of the total power losses.



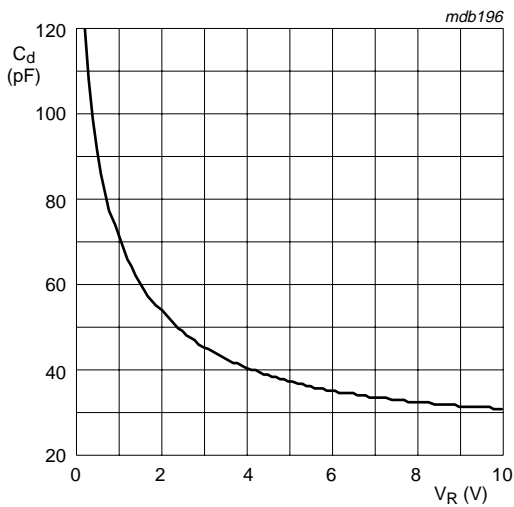
- (1)  $T_{amb} = 85\text{ }^{\circ}\text{C}$
- (2)  $T_{amb} = 25\text{ }^{\circ}\text{C}$
- (3)  $T_{amb} = -40\text{ }^{\circ}\text{C}$

Fig 1. Forward current as a function of forward voltage; typical values



- (1)  $T_{amb} = 85\text{ }^{\circ}\text{C}$
- (2)  $T_{amb} = 25\text{ }^{\circ}\text{C}$
- (3)  $T_{amb} = -40\text{ }^{\circ}\text{C}$

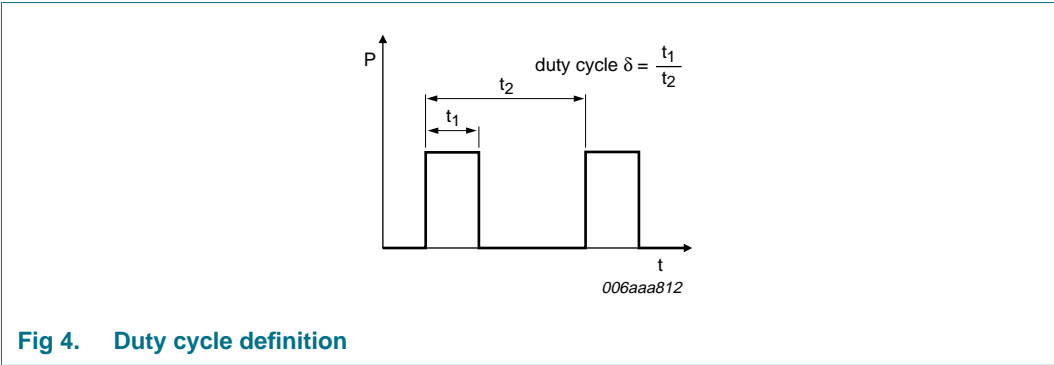
Fig 2. Reverse current as a function of reverse voltage; typical values



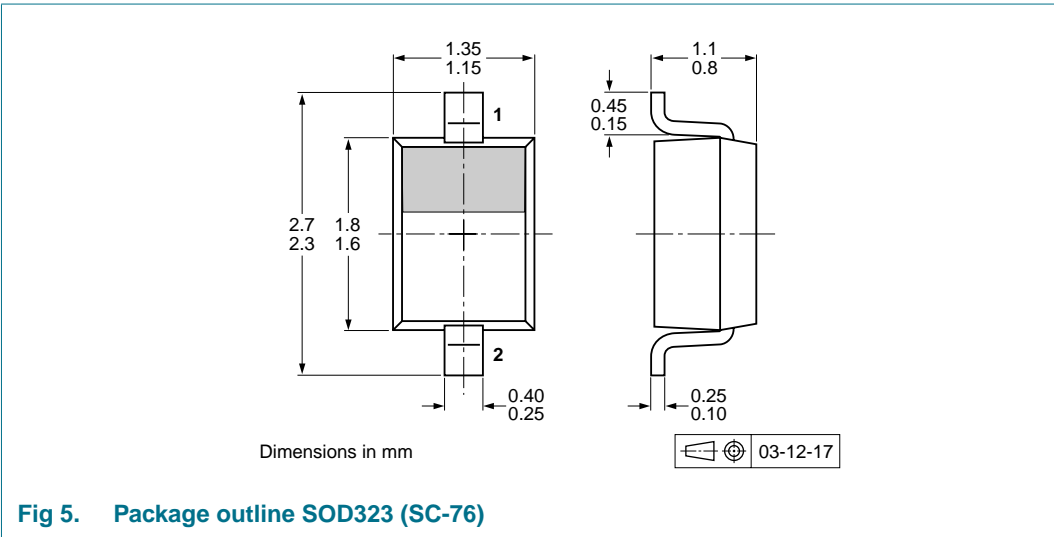
$f = 1\text{ MHz}$ ;  $T_{amb} = 25\text{ }^{\circ}\text{C}$

Fig 3. Diode capacitance as a function of reverse voltage; typical values

8. Test information



9. Package outline



10. Packing information

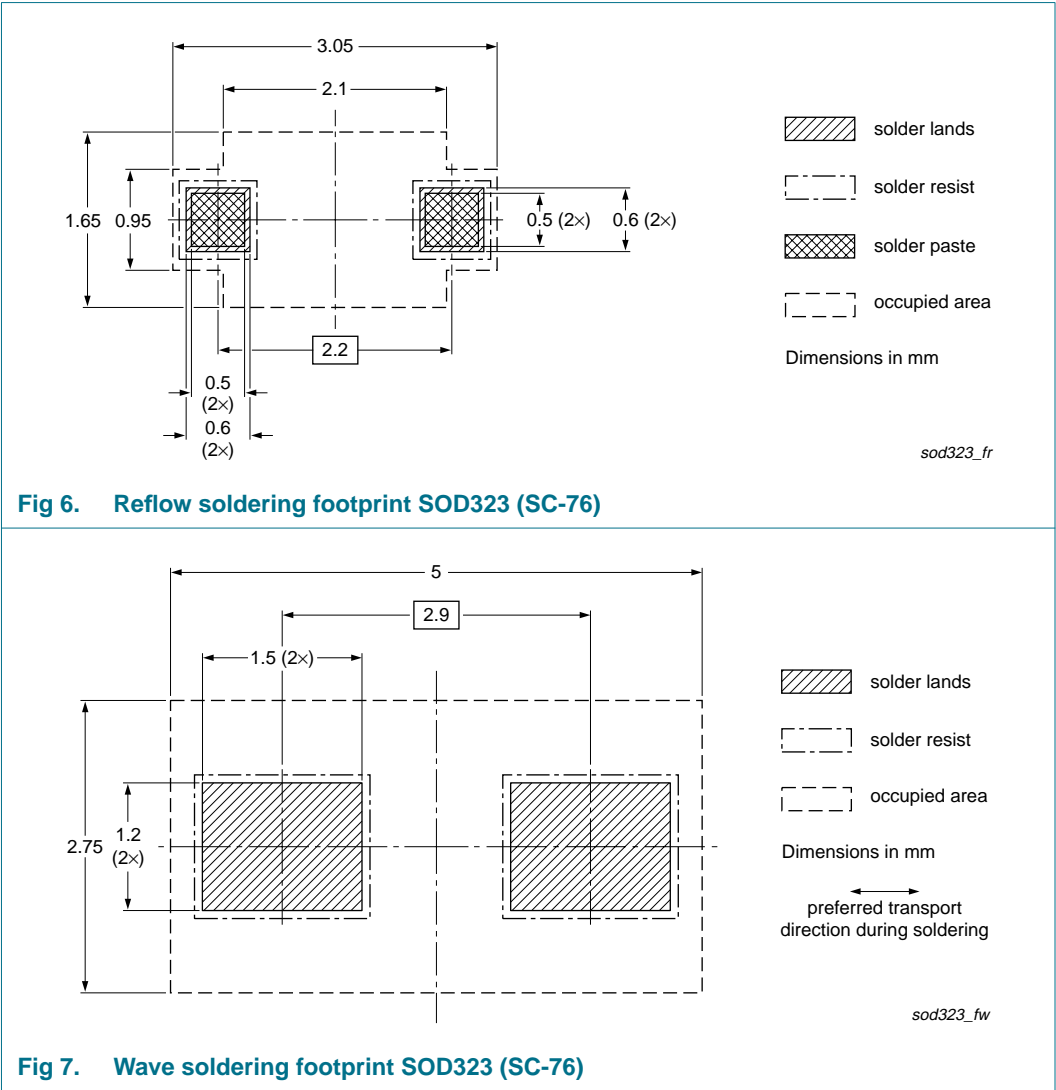
**Table 8. Packing methods**

The indicated -xxx are the last three digits of the 12NC ordering code.<sup>[1]</sup>

| Type number | Package | Description                    | Packing quantity |       |
|-------------|---------|--------------------------------|------------------|-------|
|             |         |                                | 3000             | 10000 |
| PMEG1020EA  | SOD323  | 4 mm pitch, 8 mm tape and reel | -115             | -135  |

[1] For further information and the availability of packing methods, see [Section 14](#).

11. Soldering



## 12. Revision history

**Table 9.** Revision history

| Document ID    | Release date   | Data sheet status         | Change notice | Supersedes   |
|----------------|--|---------------------------|---------------|--------------|
| PMEG1020EA_4   | 20081230   | Product data sheet        | -             | PMEG1020EA_3 |
| Modifications: | <ul style="list-style-type: none"><li>• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li><li>• Legal texts have been adapted to the new company name where appropriate.</li><li>• <a href="#">Section 13 “Legal information”</a>: updated</li></ul> |                           |               |              |
| PMEG1020EA_3   | 20040206   | Product specification     | -             | PMEG1020EA_2 |
| PMEG1020EA_2   | 20030715   | Product specification     | -             | PMEG1020EA_1 |
| PMEG1020EA_1   | 20030307   | Preliminary specification | -             | -            |



## 13. Legal information

### 13.1 Data sheet status

| Document status <sup>[1][2]</sup> | Product status <sup>[3]</sup> | Definition  |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet      | Development                   | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet    | Qualification                 | This document contains data from the preliminary specification.                       |
| Product [short] data sheet        | Production                    | This document contains the product specification.                                     |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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